

IEEE/SICE SII 2024

International Symposium on System Integration HA LONG, VIETNAM 8-11th January, 2024









Ha Long Bay

IEEE/SICE International Symposium on System Integration (SII) is the symposium series presenting the state of the art and future perspectives of system integration, where industrial experts, researchers, and academics share ideas and experiences surrounding frontier technologies, breakthrough and innovative solutions, and applications.

The IEEE/SICE SII 2024 will be the 16th symposium on system integration. System integration is one of the key technologies and the integration of hardware and software is especially important to solve the industrial or social system problems in the new century. This symposium focuses towards new research and industrial applications of system integration, and discusses approaches and methodologies to improve effectiveness of system integration.

Important Dates:

Proposals for Special Sessions Jun. 30, 2023 Aug. 1, 2023 Paper Submission Oct. 1,2023 Notification of Paper Acceptance Oct. 15, 2023 Final Paper Submission Late Breaking Results Oct. 15, 2023 Oct. 29, 2023 Notification Result of Late Breaking Results Workshop Paper Submission Deadline Aug.15, 2023 Notification Result of Workshop Paper Results Sep.15, 2023



FOLLOW US!

@SII2024_HaLong

Contact: sii2024@ml.jaist.ac.jp

* All proceedings will be published on IEEE Xplore, and indexed by Web of Science and Scopus.



Van Anh Ho, Japan Advanced Institute of Science and Technology, Japan. General Co-chair

Gordon Cheng, The Technical University of Munich, Germany. Jun Ueda, Georgia Institute of Technolgy, United States

Program Chair

Trung Dung Ngo, University of Prince Edward Island, Canada. Program Co-Chairs

Hung (Jim) La, University of Nevada, United States. Mochiyama Hiromi, University of Tsukuba, Japan. Matteo Bianchi, University of Pisa, Italy.

Special Sessions Chairs Mihoko Niitsuma, Chuo University, Japan.

Workshop Chair

Zhongkui Wang, Ritsumeikan Univ, Japan

Publication Chairs

Thanh Nho Do, The University of New South Wales, Australia. Yongsheng Ou, Chinese Academy of Sciences. Industry Chair

Son Tong, Siemens, Belgium.

Publicity Chair

Amy Kyungwon Han, Seoul National University, Korea.

Local Arrangement
Thanh Tung Bui, VNU University of Engineering and Technology, Vietnam.

Financial Chairs
Pham Hung, VNU University of Engineering and Technology, Vietnam. Dinh Quang Nguyen, Hanoi University of Industry, Vietnam.

Regional Chairs

Kumeresan A. D., University of Technology Malaysia, Malaysia Wee Hong Ong, Universiti Brunei Darussalam,Brunei. John-Josef Leth, Aalborg University, Denmark.

Muhammad Iqbal, Tampere University, Finland.
Pakpong CHIRARATTANANON, City University of Hong Kong, China

Lum Guo Zhan, Nanyang Technological University, Singapore

Administrative Support Members
Nhan Huu Nguyen, Japan Advanced Institute of Science and Technology, Japan.
Dinh Minh Nhat Le, Japan Advanced Institute of Science and Technology, Japan.

Photo credit: Thanh Chung